

4(a). Subheading 3923.10.00 is deleted and the following new provisions are inserted in lieu thereof:

[3923	: Articles....]	:	:	:
"3923.10	: Boxes, cases, crates and similar articles:	:	:	:
3923.10.20	: Specially shaped or fitted for the conveyance or	:	:	:
	: packing of semiconductor wafers, masks or	:	:	:
	: reticles of subheadings 3923.10 or 8486.90.....	: [See an-	: Free (A,AU,BH, : 80%	:
		: nex II]	: CA,CL,CO,E,IL, :	:
		:	: JO,MA,MX,OM, :	:
		:	: P,PA,PE,SG) :	:
		:	: 1.5% (KR) :	:
3923.10.90	: Other.....	: 3%	: Free (A,AU,BH, : 80%"	:
		:	: CA,CL,CO,E,IL, :	:
		:	: JO,MA,MX,OM, :	:
		:	: P,PA,PE,SG) :	:
		:	: 1.5% (KR) :	:

(b) The duty rates in the "Rates of Duty 1-Special" subcolumn followed by the symbol "(KR)" for subheadings 3923.10.20 and 3923.10.90 shall each be deleted at the close of December 31 on each of the following years, and the rate of duty set forth opposite each such year shall be inserted effective for goods of Korea in lieu thereof in each such subheading:

2017	1.2%
2018	0.9%
2019	0.6%
2020	0.3%
2021	Free

5. Chapter 84 is modified by inserting in numerical sequence the following new additional U.S. note 5:

- "5. For purposes of this chapter, the expression "goods described in additional U.S. note 5 to this chapter" are multi-component integrated circuits (MCOs), comprising a combination of one or more monolithic, hybrid, and/or multi-chip integrated circuits with at least one of the following components: silicon-based sensors, actuators, oscillators, resonators or combinations thereof, or components performing the functions of articles classifiable under heading 8532, 8533, 8541, or inductors classifiable under heading 8504, formed to all intents and purposes indivisibly into a single body like an integrated circuit, as a component of a kind used for assembly onto a printed circuit board (PCB) or other carrier, through the connecting of pins, leads, balls, lands, bumps, or pads.

For the purpose of this definition :

1. "Components" may be discrete, manufactured independently then assembled onto the rest of the MCO, or integrated into other components.

2. "Silicon based" means built on a silicon substrate, or made of silicon materials, or manufactured onto integrated circuit die.
3. (a) "Silicon based sensors" consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of detecting physical or chemical quantities and transducing these into electric signals, caused by resulting variations in electric properties or displacement of a mechanical structure. "Physical or chemical quantities" relates to real world phenomena, such as pressure, acoustic waves, acceleration, vibration, movement, orientation, strain, magnetic field strength, electric field strength, light, radioactivity, humidity, flow, chemicals concentration, etc.
- (b) "Silicon based actuators" consist of microelectronic and mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of converting electrical signals into physical movement.
- (c) "Silicon based resonators" are components that consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and have the function of generating a mechanical or electrical oscillation of a predefined frequency that depends on the physical geometry of these structures in response to an external input.
- (d) "Silicon based oscillators" are active components that consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of generating a mechanical or electrical oscillation of a predefined frequency that depends on the physical geometry of these structures."

6. Subheading 8414.59 is modified by inserting in numerical sequence the following new provision, and by redesignating subheading 8414.59.60 as 8414.59.65:

[8414	:Air...:]	:	:	:
:	[Fans:]	:	:	:
[8414.59	: Other:]	:	:	:
"8414.59.15	: Fans of a kind used solely or principally for	:	:	:
:	cooling microprocessors, telecommunica-	:	:	:
:	tions apparatus, automatic data processing	:	:	:
:	machines or units of automatic data	:	:	:
:	processing machines.....	: Free	:	: 35%"

7. Subheading 8423.20.00 is deleted and the following new provisions are inserted in numerical sequence: